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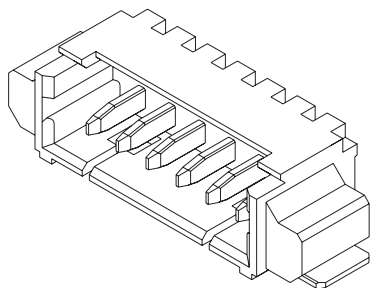
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Jameco Part Number 1932563

1.25mm (.049") Pitch PicoBlade™ Wire-to-Board Header

53261
Right Angle, SMT



Features and Benefits

- Sizes 2 to 15 circuits
- Locking windows provide secure mating
- Metal solder tabs provide PCB hold-down and strain relief for SMT tails

Reference Information

Packaging: Embossed tape
UL File No.: E29179
CSA File No.: LR19980
Mates With: 51021
Designed In: Millimeters

Electrical

Voltage: 125V
Current: 1.0A (32 AWG—0.8A)
Contact Resistance: 20 milliohms max.
Dielectric Withstanding Voltage: 250V AC/1 min.
Insulation Resistance: 100 Megohms min.

Physical

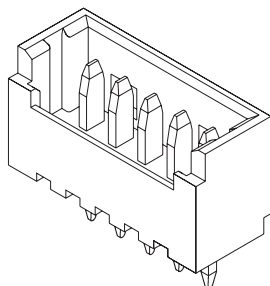
Housing: 4/6 nylon, UL 94V-0
Contact: Phosphor Bronze
Plating: Tin
Solder Tabs: Phosphor Bronze, Tin plating
Operating Temperature: -40 to +85°C

Circuits	Order No.	Carrier Tape Width	Lead-free
2	53261-0271	16.00 (.630)	Yes
3	53261-0371		
4	53261-0471		
5	53261-0571	24.00 (.945)	
6	53261-0671		
7	53261-0771		
8	53261-0871		
9	53261-0971		
10	53261-1071		

Circuits	Order No.	Carrier Tape Width	Lead-free
11	53261-1171	32.00 (1.260)	Yes
12	53261-1271		
14	53261-1471		
15	53261-1571	44.00 (1.732)	

1.25mm (.049") Pitch PicoBlade™ Wire-to-Board Header

53047
Vertical



Features and Benefits

- Sizes 2 to 15 circuits
- Locking windows provide secure mating

Reference Information

Packaging: Tray
Mates With: 51021
Designed In: Millimeters

Electrical

Voltage: 125V
Current: 1.0A (32 AWG—0.8A)
Contact Resistance: 20 milliohms max.
Dielectric Withstanding Voltage: 250V AC/1 min.
Insulation Resistance: 100 Megohms min.

Physical

Housing: 6/6 nylon, UL 94V-0
Contact: Phosphor Bronze
Plating: Tin
Operating Temperature: -40 to +85°C

Circuits	Order No.	Lead-free
2	53047-0210	Yes
3	53047-0310	
4	53047-0410	
5	53047-0510	
6	53047-0610	
7	53047-0710	
8	53047-0810	

Circuits	Order No.	Lead-free
9	53047-0910	Yes
10	53047-1010	
11	53047-1110	
12	53047-1210	
13	53047-1310	
14	53047-1410	
15	53047-1510	



PRODUCT SPECIFICATION



LANGUAGE
JAPANESE
ENGLISH

[1. 適用範囲 SCOPE]

本仕様書は、_____ 殿 に納入する
 1.25mmピッチ SMT基板用 コネクタ _____ について規定する。
 This specification covers the 1.25mm PITCH WIRE TO BOARD CONNECTOR series.

[2. 製品名称及び型番 PRODUCT NAME AND PART NUMBER]

製品名称 Product Name		製品型番 Part Number
ターミナル Male Terminal (AWG #26-28)	無鉛 LEAD FREE	50079-8*00
ターミナル Male Terminal (AWG #28-32)	無鉛 LEAD FREE	50058-8*00
ハウジング Housing	無鉛 LEAD FREE	51021-**00
ウェハー アッセンブリ Wafer Assembly (R/A)	無鉛 LEAD FREE	53261-**19
ウェハー アッセンブリ Wafer Assembly (R/A)	無鉛 LEAD FREE	53261-**71 (エンボステープ入り Embossed Tape Package)
ウェハー アッセンブリ Wafer Assembly (R/A)	無鉛 LEAD FREE	53261-**78 (エンボステープ入り、シリカゲル入り梱包 Embossed Tape Package, Silicagel Package)
ウェハー アッセンブリ 黒 Wafer Assembly (R/A) BLACK	無鉛 LEAD FREE	53261-**17
ウェハー アッセンブリ 黒 Wafer Assembly (R/A) BLACK	無鉛 LEAD FREE	53261-**27 (エンボステープ入り Embossed Tape Package)
ウェハー アッセンブリ Wafer Assembly (ST.)	無鉛 LEAD FREE	53398-**19
ウェハー アッセンブリ Wafer Assembly (ST.)	無鉛 LEAD FREE	53398-**71 (エンボステープ入り Embossed Tape Package)
ウェハー アッセンブリ Wafer Assembly (ST.)	無鉛 LEAD FREE	53398-**84 (エンボステープ入り、シリカゲル入り梱包 Embossed Tape Package, Silicagel Package)

* : 図面参照 Refer to the drawing.

REV.	A	B	C	D	E	F	G	H	J										
SHEET	1-9	1-9	1-9	1-9	1-9	1-10	1-10	1-10	1-10										
REVISE ON PC ONLY							TITLE: 1.25mm PITCH WIRE TO BOARD CONNECTOR -LEAD FREE- 製品仕様書												
J	変更 REVISED J2008-0007 '07/07/02 K.SAITO						THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION												
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DESIGN CONTROL J							STATUS					DOCUMENT NUMBER PS-51021-024				FILE NAME PS51021024.doc		SHEET 1 OF 10	



PRODUCT SPECIFICATION



LANGUAGE

JAPANESE
ENGLISH

[3. 定格及び適用電線 RATINGS AND APPLICABLE WIRES]

項目 Item	規格 Standard	
最大許容電圧 Rated Voltage (MAX.)	125 V (実効値 rms)	
最大許容電流 及び適用電線 Rated Current (MAX.) and Applicable wires	AWG. #26	1.0 A
	AWG. #28	1.0 A
	AWG. #30	1.0 A
	AWG. #32	0.8 A
使用温度範囲 Ambient Temperature Range	-40°C ~ +85°C*1	

*1: 通電による温度上昇分も含む。
Including terminal temperature rise.

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J

SEE SHEET 1 OF 10

TITLE:

1.25mm PITCH WIRE TO BOARD CONNECTOR

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製品仕様書

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DESCRIPTION

DOCUMENT NUMBER

PS-51021-024

FILE NAME

PS51021024.doc

SHEET

2 OF 10

EN-37-1(019)



PRODUCT SPECIFICATION



LANGUAGE

JAPANESE
ENGLISH

[4. 性能 PERFORMANCE]

4-1. 電気的性能 ELECTRICAL PERFORMANCE

項目 Item	条件 Test Condition	規格 Requirement
4-1-1 接触抵抗 Contact Resistance	コネクタを嵌合させ、開放電圧20mV 以下、短絡電流 10mA以下にて測定する。 (JIS C5402 5.4) Mate connectors, measure by dry circuit, 20mV MAX., 10mA MAX. (JIS C5402 5.4)	20 milliohm MAX.
4-1-2 絶縁抵抗 Insulation Resistance	コネクタを嵌合させ、隣接するターミナル間及びターミナル、アース間に、DC 500V を印加し測定する。 (JIS C5402 5.2/MIL-STD-202 試験法 302B) Apply 500V DC between adjacent terminals or terminal and ground. (JIS C5402 5.2/MIL-STD-202 Method 302B)	100 Megohm MIN.
4-1-3 耐電圧 Dielectric Strength	コネクタを嵌合させ、隣接するターミナル間及びターミナル、アース間に、AC 250V (実効値) を 1 分間 印加する。 (JIS C5402 5.1/MIL-STD-202 試験法 301) Apply 250V AC(rms) between adjacent terminals or terminal and ground for 1 minute. (JIS C5402 5.1/MIL-STD-202 Method 301)	異状なきこと No Breakdown
4-1-4 圧着部接触抵抗 Contact Resistance on Crimped Portion	ターミナルに適合電線を圧着し、開放電圧 20mV 以下、短絡電流 10mA以下にて測定する。 Crimp the applicable wire to the terminal, and measure contact resistance by dry circuit, 20mV MAX., 10mA.MAX.	5 milliohm MAX.

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J

SEE SHEET 1 OF 10

TITLE:

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DOCUMENT NUMBER

PS-51021-024

FILE NAME

PS51021024.doc

SHEET

3 OF 10

EN-37-1(019)



PRODUCT SPECIFICATION



LANGUAGE
JAPANESE
ENGLISH

4-2. 機械的性能 MECHANICAL PERFORMANCE

項目 Item		条件 Test Condition	規格 Requirement	
4-2-1	挿入力 及び抜去力 Insertion and Withdrawal Force	毎分 25±3mm の速さで挿入、抜去を行う。 Insert and withdraw connectors at the speed rate of 25±3mm/minute.	第 7 参照 Refer to paragraph 7	
4-2-2	圧着部 引張り強度 Crimping Strength	圧着されたターミナルを治具に固定し、電線 を軸方向に毎分25±3mm の速さで引張る。 (JIS C5402 6.8) Fix the crimped terminal, apply axial pull out force on the wire at the speed rate of 25± 3mm/minute. (JIS C5402 6.8)	AWG. #26	9.8 N {1.0kgf} MIN.
			AWG. #28	9.8 N {1.0kgf} MIN.
			AWG. #30	4.9 N {0.5kgf} MIN.
			AWG. #32	3.0 N {0.3kgf} MIN.
4-2-3	ターミナル 挿入力 Terminal Insertion Force	圧着されたターミナルをハウジングに挿入す る。 Insert the crimped terminal into the housing.	4.9 N {0.5kgf} MAX.	
4-2-4	ターミナル 保持力 Terminal/ Housing Retention Force	圧着されたターミナルをハウジングに装着 し、電線を軸方向に毎分 25±3mm の速さで 引張る。 Apply axial pull out force to the terminal assembled in the housing at the speed rate of 25±3mm/minute.	4.9 N {0.5kgf} MIN.	
4-2-5	ピン保持力 Pin Retention Force	毎分 25±3mm の速さで ピンを軸方向に 押す。 Apply axial push force at the speed rate of 25±3mm/minute.	4.9 N {0.5kgf} MIN.	

REVISE ON PC ONLY		TITLE: 1.25mm PITCH WIRE TO BOARD CONNECTOR -LEAD FREE- 製品仕様書
J	SEE SHEET 1 OF 10	
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DOCUMENT NUMBER PS-51021-024		FILE NAME PS51021024.doc
		SHEET 4 OF 10



PRODUCT SPECIFICATION



LANGUAGE

JAPANESE
ENGLISH

4-3. その他 OTHERS

項目 Item		条件 Test Condition	規格 Requirement	
4-3-1	繰り返し挿抜 Repeated Insertion/ Withdrawal	1分間に10回以下の速さで挿入、抜去を30回繰り返す。 When mated up to 30 cycles repeatedly by the rate of 10 cycles per minute.	接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-2	温度上昇 Temperature Rise	コネクタを嵌合させ、最大許容電流を通电し、コネクタの温度上昇分を測定する。 (UL 498) Carrying rated current load. (UL 498)	温度上昇 Temperature Rise	30°C MAX.
4-3-3	耐振動性 Vibration	DC 1mA 通电状態にて、嵌合軸を含む互いに垂直な3方向に掃引割合10~55~10Hz/分全振幅1.5mmの振動を各2時間加える。 (JIS C60068-2-6/MIL-STD-202 試験法 201) Amplitude : 1.5mm P-P Sweep time : 10-55-10 Hz in 1 minute Duration : 2 hours in each X.Y.Z. axes (JIS C60068-2-6/MIL-STD-202 Method 201)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
			瞬断 Discontinuity	1.0 microsecond MAX.
4-3-4	耐衝撃性 Shock	DC 1mA 通电状態にて、嵌合軸を含む互いに垂直な6方向に490m/s ² {50G}、の衝撃を各3回加える。 (JIS C60068-2-27/MIL-STD-202 試験法213) 490m/s ² {50G}, 3 strokes in each X.Y.Z. axes. (JIS C60068-2-27 MIL-STD-202 Method 213)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
			瞬断 Discontinuity	1.0 microsecond MAX.
4-3-5	耐熱性 Heat Resistance	コネクタを嵌合させ、85±2°Cの雰囲気中に96時間放置後取出し、1~2時間室温に放置する。 (JIS C60068-2-2/MIL-STD-202 試験法108) 85±2°C, 96 hours (JIS C60068-2-2/MIL-STD-202 Method 108)	外観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.

REVISE ON PC ONLY

J

SEE SHEET 1 OF 10

TITLE:

1.25mm PITCH WIRE TO BOARD CONNECTOR

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DOCUMENT NUMBER

PS-51021-024

FILE NAME

PS51021024.doc

SHEET

5 OF 10

EN-37-1(019)



PRODUCT SPECIFICATION



LANGUAGE

JAPANESE
ENGLISH

項目 Item		条件 Test Condition	規格 Requirement	
4-3-6	耐寒性 Cold Resistance	コネクタを嵌合させ、-40±3℃ の雰囲気中に96時間 放置後取出し、1~2時間 室温に放置する。 (JIS C60068-2-1) -40±3℃, 96 hours (JIS C60068-2-1)	外 観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-7	耐湿性 Humidity	コネクタを嵌合させ、60±2℃、相対湿度 90~95% の雰囲気中に 96時間 放置後取出し、1~2時間 室温に放置する。 (JIS C60068-2-3/MIL-STD-202試験法103) Temperature : 60±2℃ Relative Humidity : 90~95% Duration : 96 hours (JIS C60068-2-3/MIL-STD-202 Method 103)	外 観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
			耐電圧 Dielectric Strength	4-1-3項を 満たすこと Must meet 4-1-3
			絶縁抵抗 Insulation Resistance	10 Megohm MIN.
4-3-8	温度サイクル Temperature Cycling	コネクタを嵌合させ、-55℃ に 30分、+105℃ に 30分 これを 1サイクル とし、5サイクル 繰り返す。但し、温度移行時間は 5分以内 とする。 試験後、1~2時間 室温に放置する。 (JIS C0025) 5 cycles of : a) - 55℃ 30 minutes b) +105℃ 30 minutes (JIS C0025)	外 観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-9	塩水噴霧 Salt Spray	コネクタを嵌合させ、35±2℃ にて 5±1% 重量比の塩水を 48±4時間 噴霧し、試験後常温で水洗いした後、室温で乾燥させる。 (JIS C60068-2-11/MIL-STD-202 試験法101) 48±4 hours exposure to a salt spray from the 5±1% solution at 35±2℃. (JIS C60068-2-11/MIL-STD-202 Method 101)	外 観 Appearance	異常なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.

REVISE ON PC ONLY

J

SEE SHEET 1 OF 10

TITLE:

1.25mm PITCH WIRE TO BOARD CONNECTOR

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DOCUMENT NUMBER

PS-51021-024

FILE NAME

PS51021024.doc

SHEET

6 OF 10

EN-37-1(019)



PRODUCT SPECIFICATION



LANGUAGE

JAPANESE
ENGLISH

項目 Item		条件 Test Condition	規格 Requirement	
4-3-10	耐亜硫酸ガス SO ₂ Gas	コネクタを嵌合させ、40±2°C にて 50±5ppm の亜硫酸ガス中に 24時間 放置する。 24 hours expose to 50±5ppm . SO ₂ gas at 40±2°C.	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-11	耐アンモニア性 NH ₃ Gas	コネクタを嵌合させ、濃度 28% のアンモニア水を入れた容器中に 40分間 放置する。 (1Lに対して25mLの割合) 40 minutes exposure to NH ₃ gas evaporating from 28% Ammonia solution.	外 観 Appearance	異状なきこと No Damage
			接触抵抗 Contact Resistance	40 milliohm MAX.
4-3-12	半田付け性 Solderability	端子先端より 0.5mm迄、及び金具先端を 245 ±3°C の半田に 3±0.5秒 浸す。 Soldering Time : 3±0.5 sec. Solder Temperature : 245±3°C 0.5mm from terminal tip and fitting nail tip.	濡れ性 Solder Wetting	浸漬面積の 95%以上 95% of immersed area must show no voids, pin holes
4-3-13	半田耐熱性 Resistance To Soldering Heat	(リフロー時) 第6項の条件を2回繰り返す。 <u>When reflowing</u> Repeat paragraph 6, condition two times.	端子ガタ、割れ等 異状なきこと No Damage	
		(手半田) 端子先端より 0.5mm迄、及び金具先端を、370 ~400°C の半田ゴテにて、最大5秒 加熱する。 <u>Soldering iron method</u> Soldering time : 5 sec. MAX. Solder temperature : 370~400°C 0.5mm from terminal tip and fitting nail tip		

() : 参考規格 Reference Standard
{ } : 参考単位 Reference Unit

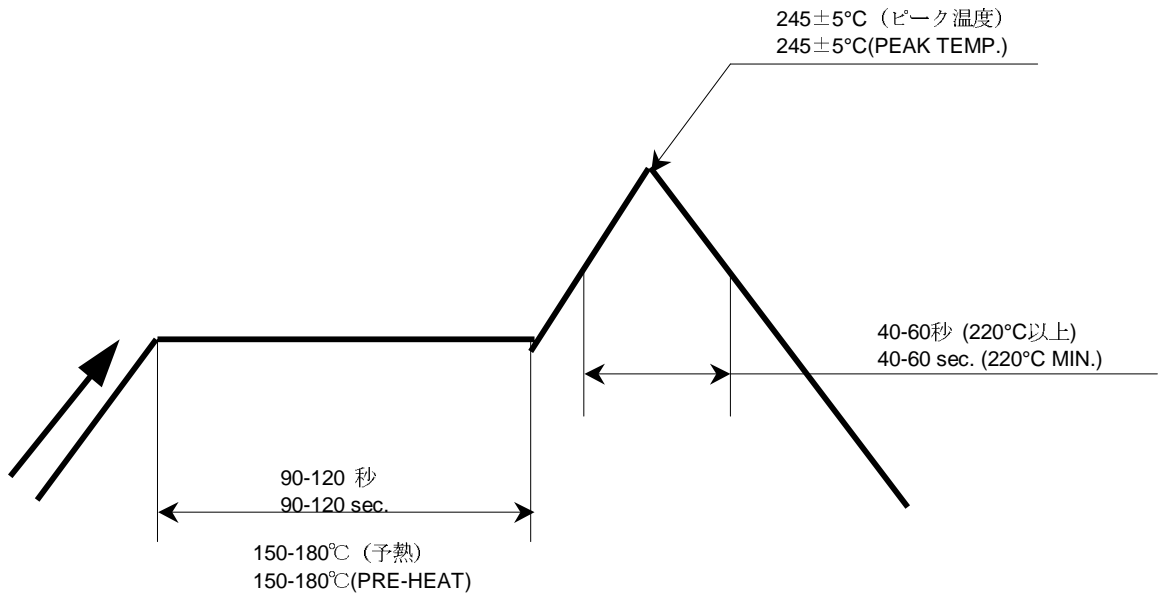
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J	SEE SHEET 1 OF 10	1.25mm PITCH WIRE TO BOARD CONNECTOR	
		-LEAD FREE- 製品仕様書	
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DOCUMENT NUMBER PS-51021-024		FILE NAME PS51021024.doc	SHEET 7 OF 10



[5. 外観形状、寸法及び材質 PRODUCT SHAPE, DIMENSIONS AND MATERIALS]

図面参照 Refer to the drawing.

[6. 赤外線リフロー条件 INFRARED REFLOW CONDITION]



温度条件グラフ
 (温度は基板パターン面)
 TEMPERATURE CONDITION GRAPH
 (TEMPERATURE ON THE SURFACE OF P.C.BOARD PATTERN)

注記 ; 本リフロー条件に関しては、リフロー装置及び基板などにより条件が異なりますので、
 事前にリフロー評価の確認をお願い致します。

また吸湿などの前処理は行わないで下さい。

NOTE ; Please check the reflow soldering condition by your own devices beforehand.
 Because the condition changes by the soldering devices, P.C.Boards, and so on.
 No moisture treatment before reflow process.

REVISE ON PC ONLY		TITLE:	
J	SEE SHEET 1 OF 10	1.25mm PITCH WIRE TO BOARD CONNECTOR	
		-LEAD FREE- 製品仕様書	
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DOCUMENT NUMBER PS-51021-024		FILE NAME PS51021024.doc	SHEET 8 OF 10



PRODUCT SPECIFICATION



LANGUAGE

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[7. 挿入力及び抜去力 INSERTION / WITHDRAWAL FORCE]

極数 No. of CKT.	単位 Unit	挿入力 (最大値) Insertion force (MAX.)			抜去力 (最小値) Withdrawal force (MIN.)		
		初回 1st	6回目 6th	30回目 30th	初回 1st	6回目 6th	30回目 30th
2	N { kgf }	19.6 { 2.0 }	17.6 { 1.8 }	15.6 { 1.6 }	2.8 { 0.28 }	2.3 { 0.23 }	1.8 { 0.18 }
3	N { kgf }	24.5 { 2.5 }	22.5 { 2.3 }	20.5 { 2.1 }	3.0 { 0.30 }	2.5 { 0.25 }	2.0 { 0.20 }
4	N { kgf }	29.4 { 3.0 }	27.4 { 2.8 }	25.4 { 2.6 }	3.3 { 0.33 }	2.8 { 0.28 }	2.3 { 0.23 }
5	N { kgf }	34.3 { 3.5 }	32.3 { 3.3 }	30.3 { 3.1 }	3.8 { 0.38 }	3.3 { 0.33 }	2.8 { 0.28 }
6	N { kgf }	39.2 { 4.0 }	37.2 { 3.8 }	35.2 { 3.6 }	4.3 { 0.43 }	3.8 { 0.38 }	3.3 { 0.33 }
7	N { kgf }	44.1 { 4.5 }	42.1 { 4.3 }	40.1 { 4.1 }	4.7 { 0.48 }	4.3 { 0.43 }	3.8 { 0.38 }
8	N { kgf }	49.0 { 5.0 }	47.0 { 4.8 }	45.0 { 4.6 }	5.2 { 0.53 }	4.7 { 0.48 }	4.3 { 0.43 }
9	N { kgf }	53.9 { 5.5 }	51.9 { 5.3 }	49.9 { 5.1 }	5.5 { 0.56 }	5.0 { 0.51 }	4.5 { 0.46 }
10	N { kgf }	58.8 { 6.0 }	56.8 { 5.8 }	54.8 { 5.6 }	5.8 { 0.59 }	5.3 { 0.54 }	4.8 { 0.49 }
11	N { kgf }	63.7 { 6.5 }	61.7 { 6.3 }	59.7 { 6.1 }	6.1 { 0.62 }	5.6 { 0.57 }	5.1 { 0.52 }
12	N { kgf }	68.6 { 7.0 }	66.6 { 6.8 }	64.6 { 6.6 }	6.4 { 0.65 }	5.9 { 0.60 }	5.4 { 0.55 }
13	N { kgf }	73.5 { 7.5 }	71.5 { 7.3 }	69.5 { 7.1 }	6.7 { 0.68 }	6.2 { 0.63 }	5.7 { 0.58 }
14	N { kgf }	78.4 { 8.0 }	76.4 { 7.8 }	74.4 { 7.6 }	7.0 { 0.71 }	6.5 { 0.66 }	6.0 { 0.61 }
15	N { kgf }	83.3 { 8.5 }	81.3 { 8.3 }	79.3 { 8.1 }	7.3 { 0.74 }	6.8 { 0.69 }	6.3 { 0.64 }
17	N { kgf }	93.1 { 9.5 }	91.2 { 9.3 }	89.2 { 9.1 }	7.9 { 0.8 }	7.4 { 0.75 }	6.9 { 0.70 }

REV.	REV. RECORD	DATE	EC NO.	WRITTEN:	CHK:
J	REVISE ON PC ONLY	TITLE:			
	SEE SHEET 1 OF 10	1.25mm PITCH WIRE TO BOARD CONNECTOR -LEAD FREE- 製品仕様書			
REV.	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DOCUMENT NUMBER PS-51021-024			FILE NAME PS51021024.doc	SHEET 9 OF 10	



PRODUCT SPECIFICATION



LANGUAGE
JAPANESE
ENGLISH

A	RELEASED	'04/02/05	J2004-2276	E.SUZUKI	K.TOJO
B	REVISED	'04/03/10	J2004-3002	E.SUZUKI	K.TOJO
C	REVISED	'04/03/29	J2004-3401	E.SUZUKI	K.TOJO
D	REVISED	'04/07/21	J2005-0243	N.AIDA	K.TOJO
E	REVISED	'04/12/06	J2005-1671	E.SUZUKI	K.TOJO
F	REVISED	'05/02/15	J2005-2371	E.SUZUKI	K.TOJO
G	REVISED	'05/04/19	J2005-3130	N.AIDA	K.TOYODA
H	REVISED	'06/01/18	J2006-2296	N.AIDA	K.TOYODA
J	REVISED	'07/07/02	J2008-0007	K.SAITO	T.HARUYAMA

REVISE ON PC ONLY		TITLE: 1.25mm PITCH WIRE TO BOARD CONNECTOR -LEAD FREE- 製品仕様書
J	SEE SHEET 1 OF 10	
REV.	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

DOCUMENT NUMBER PS-51021-024	FILE NAME PS51021024.doc	SHEET 10 OF 10
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10 9 8 7 6 5 4 3 2 1

F

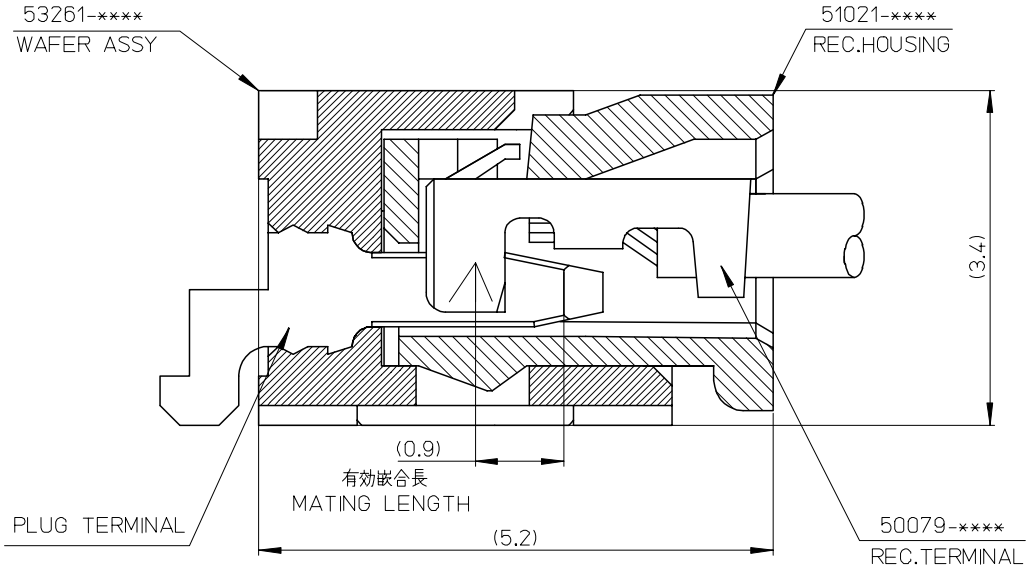
E

D

C

B

A



53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION			
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	DOCUMENT NO. SD-51021-002			
	ANGULAR	± --- °	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1			
0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9

8

7

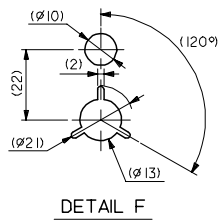
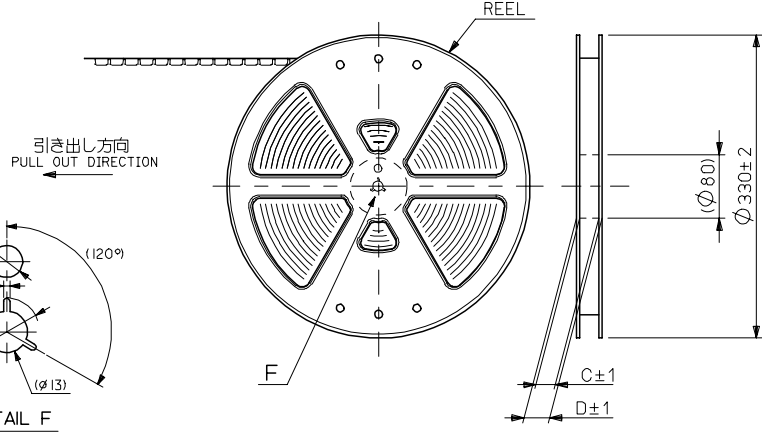
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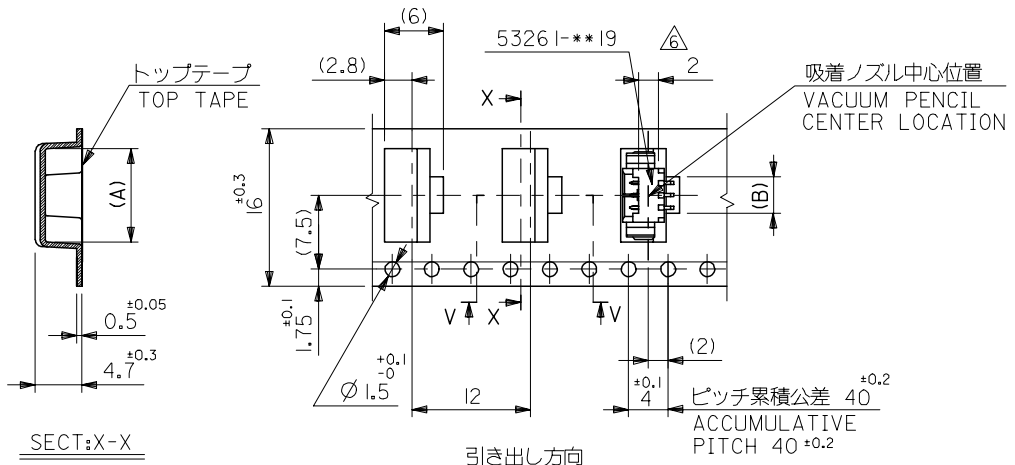
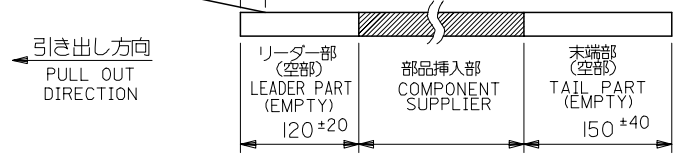
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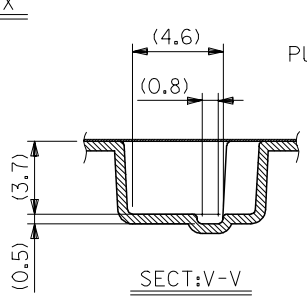
注記 NOTES

- 53261-**-19 の詳細寸法については図面 SD-53261-024 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53261-024
- 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

トップテープリーダー部 TOP TAPE LEADER PART	トップテープ未接着部 TOP TAPE NON-BONDED PART
175 ±25	25 ±5
- 材料 (MATERIAL)
 キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
 トップテープ (TOP TAPE): PET, PE, PEF
 リール (REEL): ポリスチレン (PS) <リサイクル材含む>
 POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>

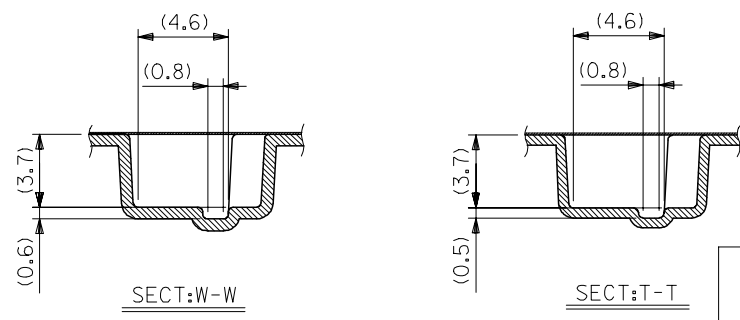
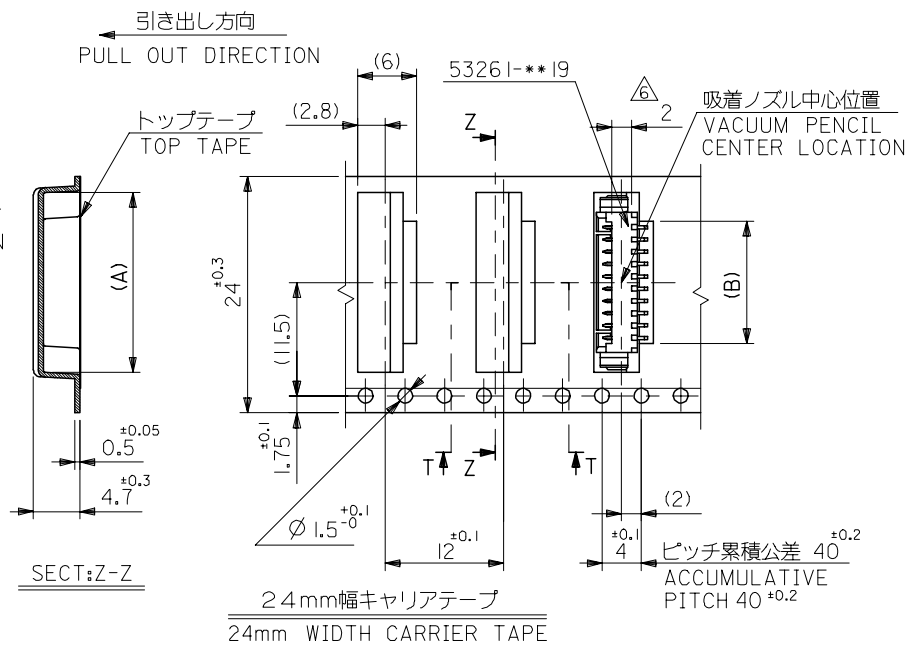
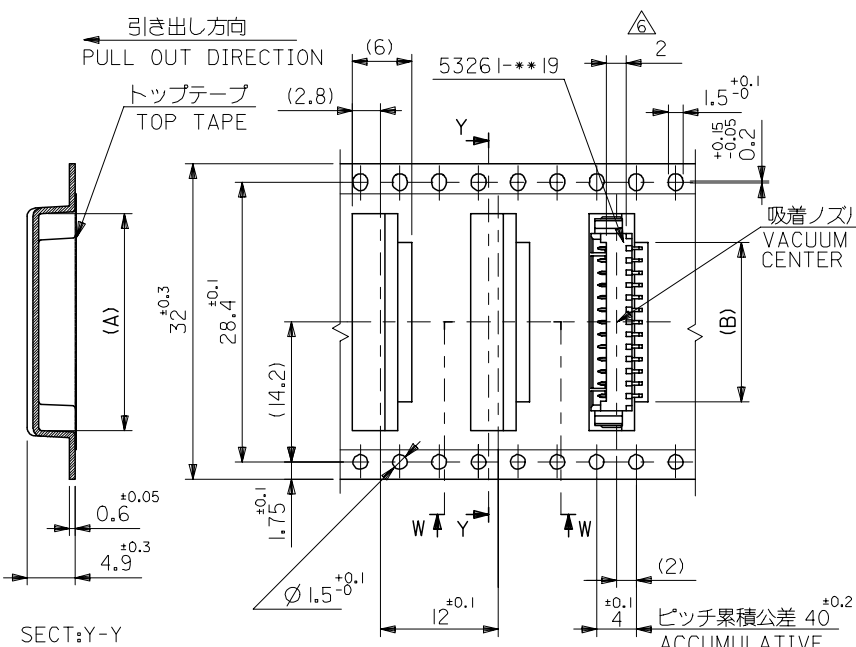


SECT:X-X



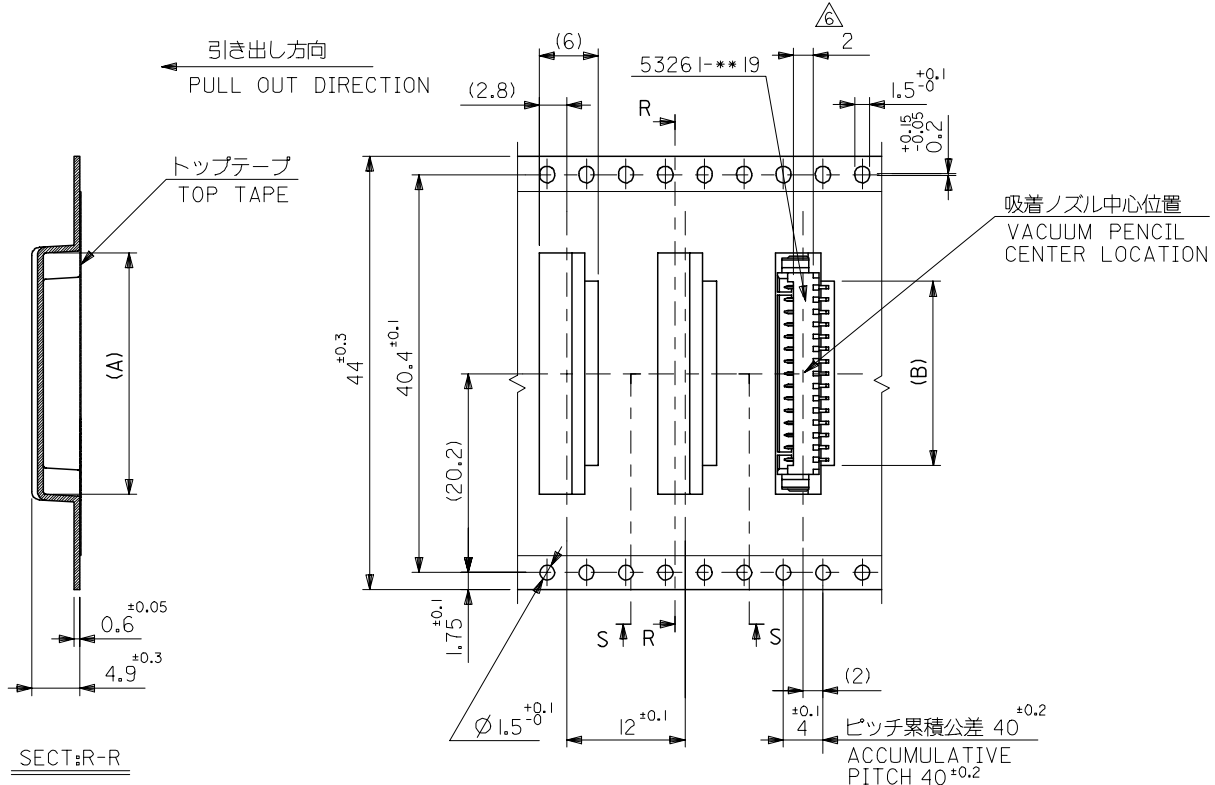
SECT:V-V

MODEL NO.	53261-**-71	16	21.4	17.4	3.7	9.5	53261-0371	3
		16mm幅キャリアテープ 16mm WIDTH CARRIER TAPE	D	C	2.45	8.25	53261-0271	2
GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
10 UNDER	±0.2	DRAWN BY DATE H. SHIMABUKUR '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG				
10 OVER 30 UNDER	±0.25	CHECKED BY DATE K. TOJO '04/02/06		MOLEX INCORPORATED				
30 OVER	±0.3	APPROVED BY DATE M. SASAO '04/02/06						
ANGULAR	±3 °	MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-53261-023		1 OF 3		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

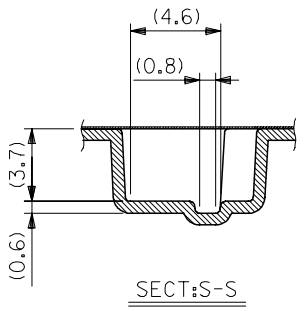


32	37.4	33.4	16.2	22	53261-1371	13	
			14.95	20.75	-1271	12	
24	29.4	25.4	13.7	19.5	-1171	11	
			12.45	18.25	-1071	10	
			11.2	17	-0971	9	
			9.95	15.75	-0871	8	
			8.7	14.5	-0771	7	
			7.45	13.25	-0671	6	
			6.2	12	-0571	5	
4.95	10.75	53261-0471	4				
キャリアテープ幅 CARRIER TAPE WIDTH		D	C	B	A	MATERIAL. NO.	種数 CKT.

MODEL NO. 53261-***71		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
GENERAL TOLERANCES (UNLESS SPECIFIED)		DRAWN BY H. SHIMABUKUR		DATE '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG	
10 UNDER	±0.2	CHECKED BY K. TOJO		DATE '04/02/06		APPROVED BY M. SASAO	
10 OVER 30 UNDER	±0.25	APPROVED BY M. SASAO		DATE '04/02/06		MATERIAL NO. SEE CHART	
30 OVER	±0.3	ANGULAR		±3 °		DOCUMENT NO. SD-53261-023	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SHEET NO. 2 OF 3	



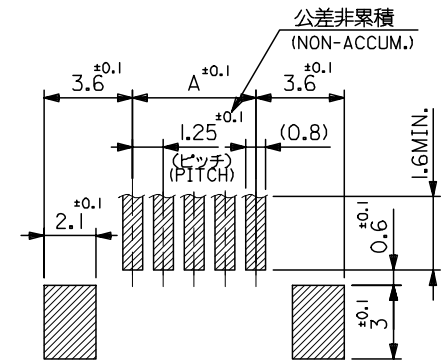
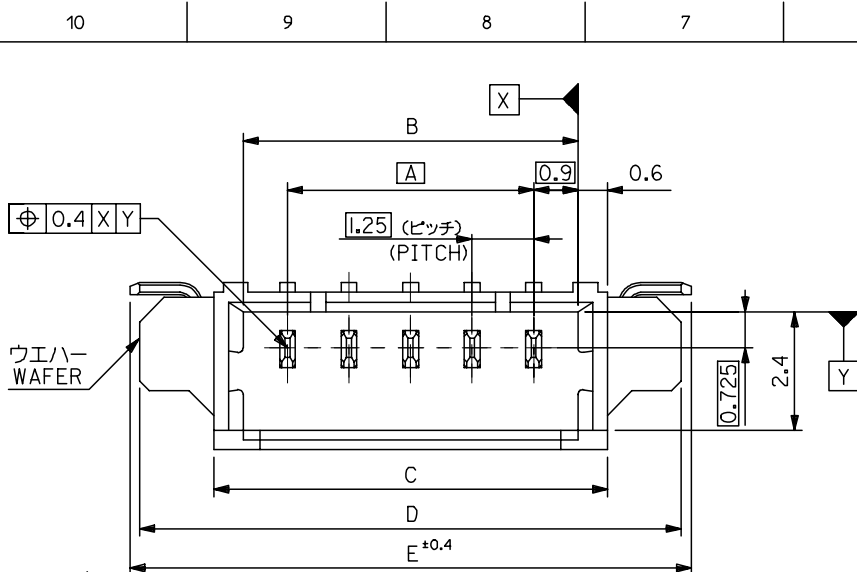
SECT:R-R



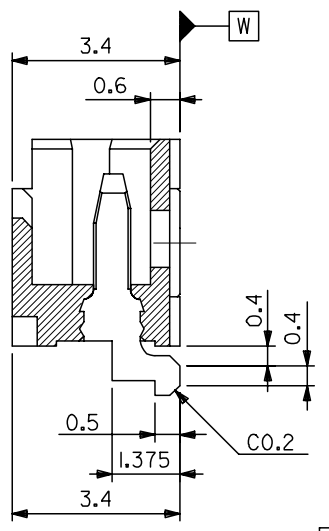
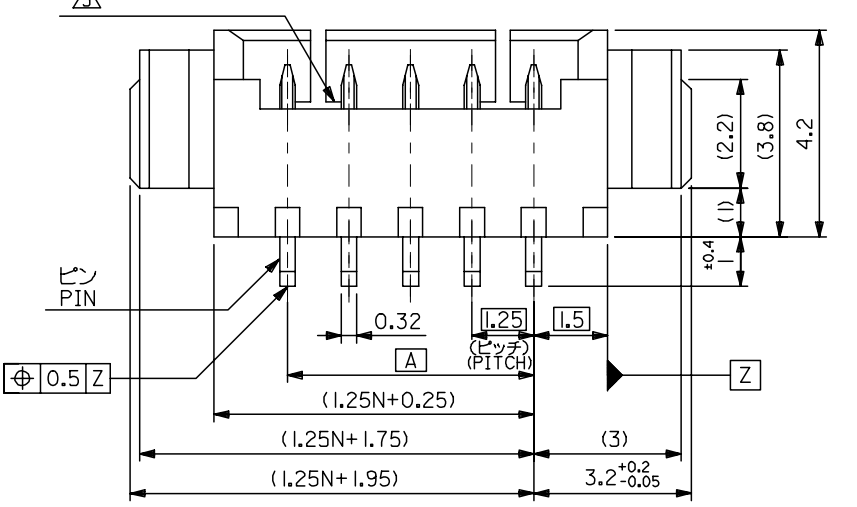
SECT:S-S

44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE

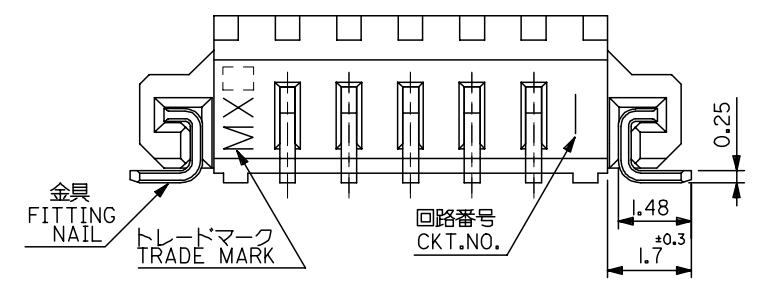
MODEL NO. 53261-**-71		44	49.4	45.4	18.7	24.5	53261-1571	15			
キャリアテープ幅 CARRIER TAPE WIDTH		D	C	B	A	MATERIAL. NO.	極致 CKT.	17.45	23.25	53261-1471	14
GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION				
10 UNDER ±0.2		DRAWN BY DATE H. SHIMABUKUR '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG		APPROVED BY DATE M. SASAO '04/02/06		MOLEX INCORPORATED			
10 OVER 30 UNDER ±0.25		CHECKED BY DATE K. TOJO '04/02/06		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
30 OVER ±0.3		APPROVED BY DATE M. SASAO '04/02/06		SEE CHART		SD-53261-023		3 OF 3			
ANGULAR ±3 °		MATERIAL NO.		SEE CHART		DOCUMENT NO.		SHEET NO.			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)
(SCALE 5:1)



[断面図]
[CROSS SECTION]



注記 NOTES

1. 嵌合相手: 51021 シリウス
MATES WITH: 51021 SERIES
2. 材質 MATERIAL
ウエハー: NYLON46, UL94V-0
ピン: リン青銅
PIN: PHOS-BRO
: 銅メッキ 1.0 マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1.0 マイクロメートル以上
: NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM
金具
FITTING NAIL: リン青銅
: PHOS-BRO
: 銅メッキ 1.0 マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1.0 マイクロメートル以上
: NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM
- △ ロック窓は2, 3極は1箇所, 4極以上は2箇所とする。
LOCKING WINDOW:
ONE PLACE FOR 2 AND 3 CKT. AND
TWO PLACES FOR MORE THAN 3 CKT.
4. ソルダータール部のスレ量及び金具(補強板)のスレ量は基準面[W]に対し、上方向0.05 MAX、下方向に0.1 MAX.とする。[W] OFFSET BETWEEN BASIS PLANE TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:
UPPER SIDE: 0.05MAX.
LOWER SIDE: 0.1MAX.
5. 本製品は 53261-**-10 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**-10

26.4	26	23	21.8	20	53261-1719	17	
23.9	23.5	20.5	19.3	17.5	-1519	15	
22.65	22.25	19.25	18.05	16.25	-1419	14	
21.4	21	18	16.8	15	-1319	13	
20.15	19.75	16.75	15.55	13.75	-1219	12	
18.9	18.5	15.5	14.3	12.5	-1119	11	
17.65	17.25	14.25	13.05	11.25	-1019	10	
16.4	16	13	11.8	10	-0919	9	
15.15	14.75	11.75	10.55	8.75	-0819	8	
13.9	13.5	10.5	9.3	7.5	-0719	7	
12.65	12.25	9.25	8.05	6.25	-0619	6	
11.4	11	8	6.8	5	-0519	5	
10.15	9.75	6.75	5.55	3.75	-0419	4	
8.9	8.5	5.5	4.3	2.5	-0319	3	
53261-**-19	7.65	7.25	4.25	3.05	1.25	53261-0219	2

MODEL NO.	E	D	C	B	A	MATERIAL. NO.	極数 CKT.
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REVISED EC NO: J2005-3130 DRW:NAIDA 2005/04/19 CHK:KTOYODA 2005/04/21 APPR:NUKITA 2005/04/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMABU	DATE 04/02/06	TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 04/02/06	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 04/02/06	DOCUMENT NO. SD-53261-024		
	ANGULAR	±3 °	MATERIAL NO. SEE DRAWING		SHEET NO. 1 OF 1		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					